

CALL FOR PAPERS

58th ECTC

ELECTRONIC COMPONENTS



AND

TECHNOLOGY

CONFERENCE

May 27 – May 30, 2008

Orlando, Florida

OPTOELECTRONICS

Papers are solicited on all topics pertaining to the design, development, and technology of packaging optoelectronics and photonic components, devices, circuitry and systems

Topics of interest include:

- **High Power Optoelectronics and Fiber Laser Packaging:** High-power laser diodes, bars / stacks, and Fiber lasers – including beam combining, coupling, wavelength control, hermetic packaging and thermal issues.
- **High-Brightness LED Packaging for Lighting and Commercial Applications:** Package and optical design, assembly methods, thermal management, reliability, color temperature control, phosphor materials, and volume manufacturing.
- **Optical Component Thermal Management and Reliability:** Optical component thermal management, package design, device performance, failure modes and reliability
- **Micro-optical Packaging and Manufacturing Technology:** Low cost designs, novel optics, assembly methodology and automation technology
- **Silicon Photonics Devices and Packaging:** Optical devices in Silicon, hybrid integration, FR performance, Silicon optical waveguides, photonics circuits and packaging
- **Optical Interconnects:** Integrated optics, high-speed and parallel transceivers, board-level waveguides, optical backplanes, fiber optic connectors and hybrid integration
- **Advanced Materials for Optoelectronics:** Substrates, devices, components and assembly materials

You are invited to submit at 500-word abstract via the ECTC Website <http://www.ectc.net>

PLEASE SELECT OPTOELECTRONICS AS YOUR PRIMARY COMMITTEE FOR SUBMISSION

(You may also submit directly to the committee chairs below – please include mailing address, telephone number, FAX number and e-mail):

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Abstracts Due: October 15, 2007